

LNJ037X8ARA

Hight Bright Surface Mounting Chip LED

ESS II Type

Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	10	mA
Pulse forward current *	I_{FP}	40	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

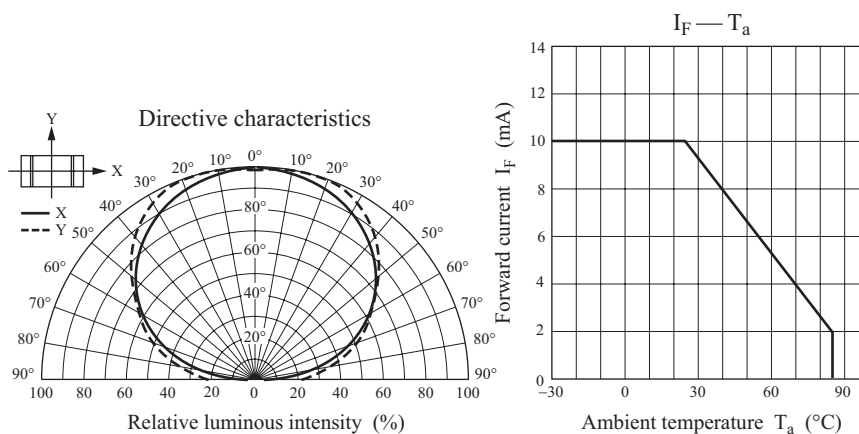
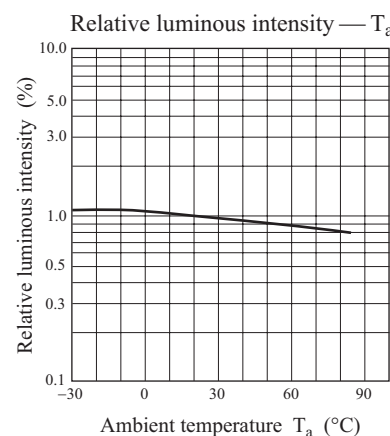
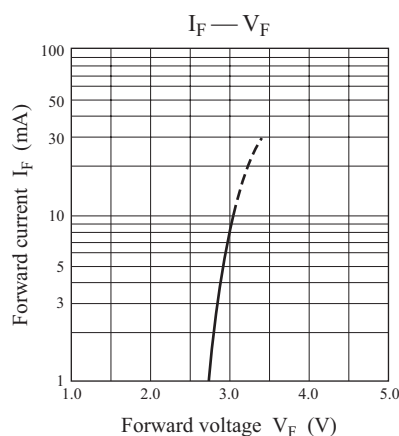
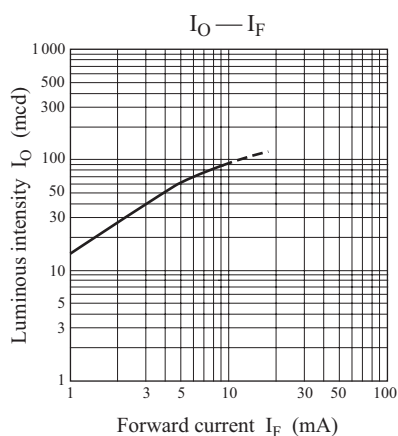
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Lighting Color

- White

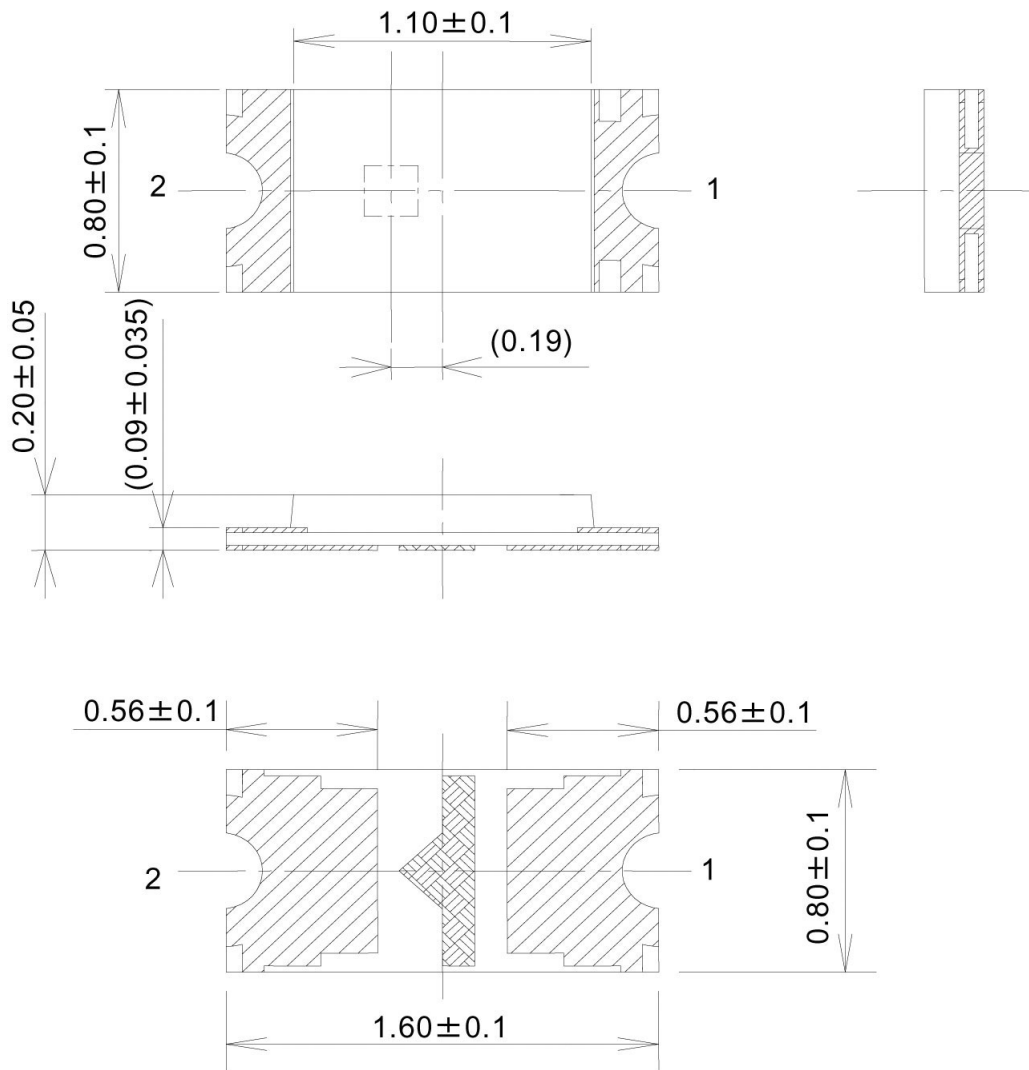
Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 5\text{ mA}$	35.0	60.0	100.0	mcd
Reverse current	I_R	$V_R = 5\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 5\text{ mA}$		2.9	3.2	V
Chromaticity coordinates	x	$I_F = 5\text{ mA}$	0.237		0.290	—
	y	$I_F = 5\text{ mA}$	0.227		0.302	—



■ Package (Unit: mm)

KLTFTN2K3700



• Pin Name

- 1: Anode
- 2: Cathode

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